



CLD SERIES

Power Modules

Features

- Flexible mounting, for Printed Circuit Board or Panel
- Low profile
- Terminals in fast on or pin format

DESCRIPTION

These modules provide complete power control in a single package, up to 42.5 Amps various circuit design with connections for printed circuit board or panel mounting. Ceramic base with 2500 Vrms isolation. UL recognition pending.

PART NUMBER IDENTIFICATION

EX.:CLDA25/12F

Circuit Type	Circuit Type	Current	Voltage
CLD - Case style	(See schematics diagram)	25 - 25 Amps	06 - 600
	Any type of Bridge	40 - 42.5 Amps	08 - 800
	Free Wheeling Diode "F"		10 - 1000
			12 - 1200

ELECTRICAL SPECIFICATION

25

40

SYMBOL	SPECIFICATION	RATINGS	
I _D	Maximum DC Output Current (T _c = 85°C)	25 Amps	42.5 Amps
V _F	Maximum Voltage Drop @ Amps Peak	1.65V @ I _F =25A	1.60V @ I _F =42.5A
T _J	Operating Junction Temperature Range	-40°C to +125°C	
di/dt	Critical Rate of Rise of On-State Current @ T _J =125°C	100A/μs	100A/μs
dv/dt	Critical Rate of Rise of Off-State Voltage [V/μs]	500V/μs	500V/μs
V _{RRM}	Repetitive Peak Reverse Voltage (AC Line)	400 (120 Vac) 600 (240 Vac) 1000 (380 Vac) 1200 (480 Vac)	
I _{TSM}	Maximum Non-Repetitive Surge Current (¹ / ₂ Cycle, 60Hz)	300A	600A
I ² T	Maximum I ² T for Fusing (t=8.3ms) [A ² sec]	375	1500
R _{qJC}	Maximum Thermal Resistance Junction to Ceramic Base per Chip	0.9°K/W	0.7°K/W
V _{ISOL}	Isolation Voltage	2500 V _{RMS}	2500 V _{RMS}

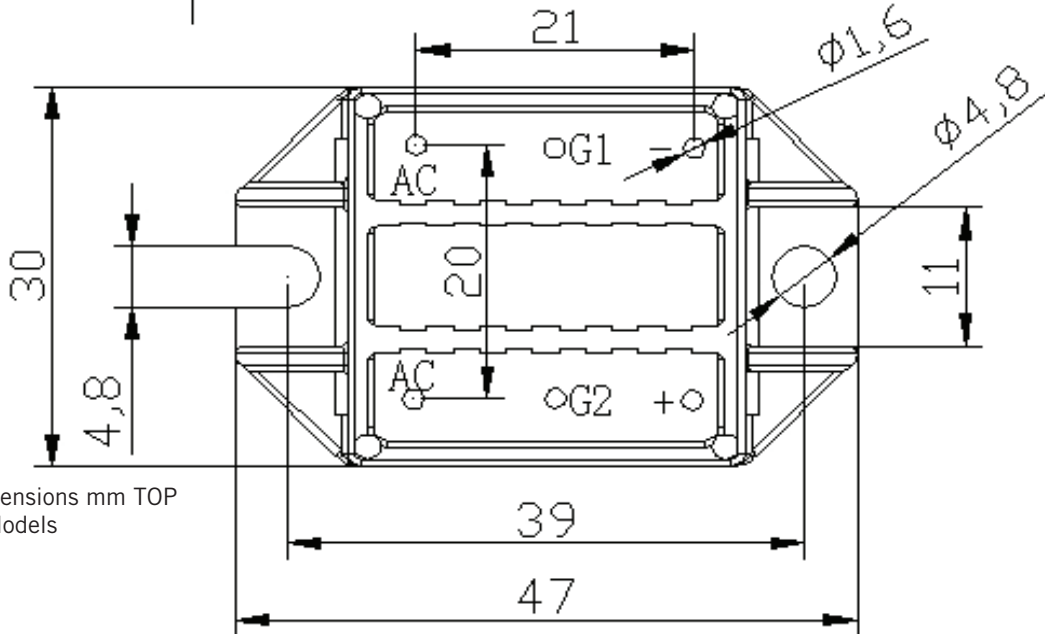
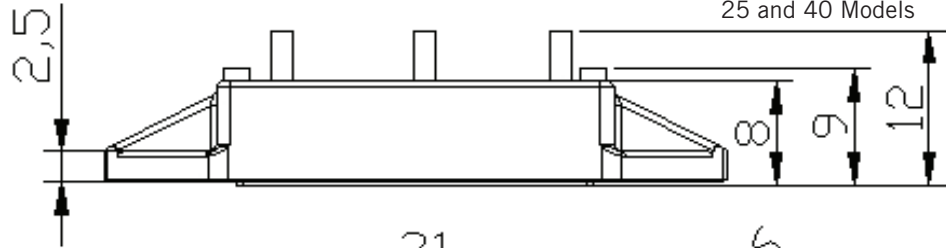
MECHANICAL SPECIFICATIONS

Weight: (typical)

1.7 oz. (43g)

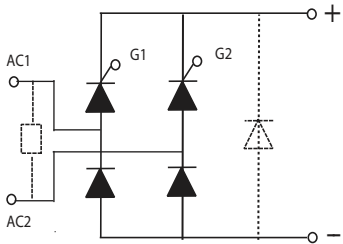
MECHANICAL DIMENSIONS AND CIRCUIT DIAGRAM

Package Dimensions mm SIDE
25 and 40 Models

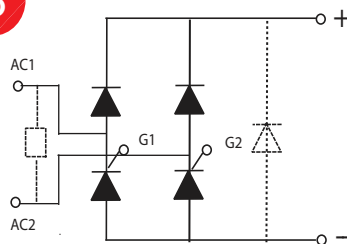


Package Dimensions mm TOP
25 and 40 Models

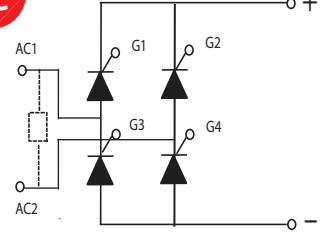
A



B



C



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